MRSI launches MRSI-705 high-volume configuration

At IMAPS 2020 MRSI Systems will introduce a new 5 micrometer die bonder product, MRSI-705 high-volume configuration. The MRSI-705 was first introduced in 2012 and has enjoyed a dominant position in the die bonding industry offering customers multiple application solutions in one machine. This new configuration offers an innovative horizontal turret feature to significantly increase the speed and throughput from the machine without sacrificing its renowned flexibility, accuracy, or reliability.

The new MRSI proprietary design delivers an “on-the-fly” tool change with up to 12 tools with zero tool changeover downtime, which has been an integral part of MRSI’s popular high-speed product lines MRSI-HVM and MRSI-H. This leads to increased machine efficiency, higher production output, and lower manufacturing costs.

This flexible 5 micrometer die bonder retains its comprehensive appeal across a wide range of applications including photonic packaging, microwave modules, RF power amplifiers, and infrared sensors.

“The addition of this new high-speed 5 micrometer die bonder re-enforces MRSI’s industry-leading position in the field of manufacturing automation for advanced microelectronic and optoelectronic devices. We look forward to working with customers to help them to scale their production,” said Dr. Yi Qian, VP & GM MRSI Systems, Myronic.

To schedule an appointment and discuss a prototype demonstration, please contact us at sales.mrsi@myronic.com.

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About MRSI Systems
MRSI Systems, part of Myronic Group, is the leading manufacturer of fully automated, high-speed, high-precision and flexible eutectic and epoxy die bonding systems. We offer “one-stop-shop” solutions for research and development, low-to-medium volume production, and high-volume manufacturing of photonic devices such as lasers, detectors, modulators, AOCs, WDM/EML TO-Cans, Optical transceivers, LiDAR, VR/AR, sensors, and optical imaging products. With 30+ years of industry experience and our worldwide local technical support team, we provide the most effective systems and assembly solutions for all packaging levels including chip-on-wafer (CoW), chip-on-carrier (CoC), PCB, and gold-box packaging. www.mrsisystems.com

About Myronic
Myronic AB is a Swedish high-tech company engaged in the development, manufacture and marketing of production equipment with high precision and flexibility requirements for the electronics industry. Myronic headquarters are located in Täby, north of Stockholm and the Group has subsidiaries in China, France, Germany, Japan, Singapore, South Korea, the Netherlands, United Kingdom and the United States. Myronic AB (publ) is listed on NASDAQ Stockholm. www.myronic.com